Panasonic

2SK2324(Tentative)

Silicon N-Channel Power F-MOS

■ Features
- Avalanche energy capability guaranteed
- High-speed switching
- Low ON-resistance
- No secondary breakdown

■ Applications
- Non-contact relay
- Solenoid drive
- Motor drive
- Control equipment
- Switching mode regulator

Unit : mm

1 : Gate
2 : Drain
3 : Source
TO-220E Package

■ Absolute Maximum Ratings (Tc = 25°C)

Parameter		Symbol	Rating	Unit
Drain-Source breakdown voltage		V_{DSS}	600	V
Gate-Source voltage		V_{GSS}	±30	V
Drain current	DC	I_D	±2	A
	Pulse	I_{DP}	±4	A
Avalanche energy capability		EAS^*	10	mJ
Allowable power dissipation	T_C= 25°C	P_D	2	W
	Ta= 25°C		40	
Channel temperature		T_{ch}	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

* L= 5mH, I_L= 2A, 1 pulse

■ Electrical Characteristics (Tc = 25°C)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Drain-Source cut-off current	I_{DSS}	V_{DS}= 480V, V_{GS}= 0			100	μA
Gate-Source leakage current	I_{GSS}	V_{GS}=± 30V, V_{DS}= 0			±1	μA
Drain-Source breakdown voltage	V_{DSS}	I_D=1mA, V_{GS}= 0	600			V
Gate threshold voltage	V_{th}	V_{DS}= 25V, I_D=1mA	2		5	V
Drain-Source ON-resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=1A		4.9	6	Ω
Forward transadmittance	$\|Y_{fs}\|$	V_{DS}= 25V, I_D=1A	0.5	0.85		S
Diode forward voltage	V_{DSF}	I_{DR}= 2A, V_{GS}= 0			−1.6	V
Input capacitance	C_{iss}			260		pF
Output capacitance	C_{oss}	V_{DS}= 20V, V_{GS}= 0, f=1MHz		35		pF
Feedback capacitance	C_{rss}			10		pF
Turn-on time (delay time)	$t_{d(on)}$			15		ns
Rise time	t_r	V_{DD}= 200V, I_D=1A		25		ns
Fall time	t_f	V_{GS}=10V, R_L= 200Ω		35		ns
Turn-off time (delay time)	$t_{d(off)}$			35		ns
Channel-Case heat resistance	$R_{th(ch-c)}$				3.125	°C/W
Channel-Atmosphere heat resistance	$R_{th(ch-a)}$				62.5	°C/W
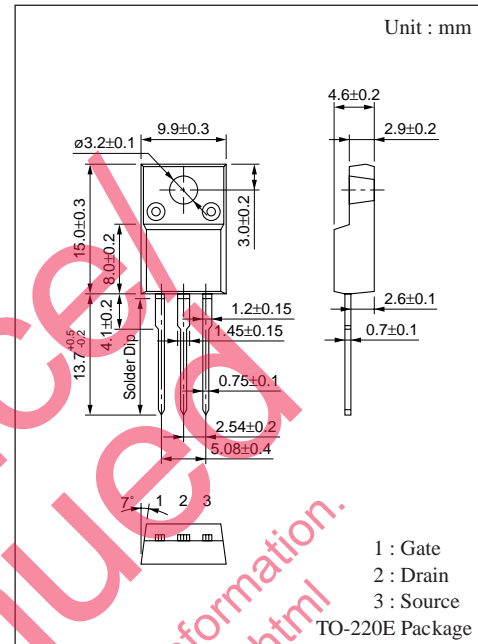
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